



Product Change Notification - GBNG-04NNSN044

Date:

15 Jun 2020

Product Category:

Access Networks

Affected CPNs:**Notification subject:**

CCB 3998 and 3998.001 Final Notice: Qualification of MMT as a new assembly site for selected Microsemi LE58QL0xxx device family available in 32L PLCC (11.5x14x3.37mm) and 44L PLCC (16.6x16.6x4.4mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as a new assembly site for selected Microsemi LE58QL0xxx device family available in 32L PLCC (11.5x14x3.37mm) and 44L PLCC (16.6x16.6x4.4mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ASEM assembly site using copper (Cu) bond wire, YIZ8143 die attach and CEL 9240HF10AK-G1 molding compound material.

Post Change:

Assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach and G600V molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ASE Group -Malaysia / ASEM	Microchip Technology Thailand (Branch) / MMT
Wire material	Cu	CuPdAu
Die attach material	YIZ8143	3280
Molding compound material	CEL 9240HF10AK-G1	G600V
Lead frame material	A194	A194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and on-time delivery by qualifying MMT as new assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date:

June 30, 2020 (date code: 2027)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and



post change parts.

Time Table Summary:

Workweek	November 2019					>	June 2020				
	44	45	46	47	48		23	24	25	26	27
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			
Estimated Implementation Date										X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

November 06, 2019: Issued initial notification.

June 15, 2020: Issued final notification. Attached is the qualification report and added the estimated first date by June 30, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-04NNSN044_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

LE58QL031DJC
LE58QL021FJC
LE58QL02FJC
LE58QL031DJCT
LE58QL021FJCT
LE58QL02FJCT